

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Jonathan A. Noquil</td><td>07/17/2007</td></tr><tr><td>Ruben Madrid</td><td>07/25/2007</td></tr></tbody></table>		Name	Execution Date	Jonathan A. Noquil	07/17/2007	Ruben Madrid	07/25/2007				
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Jonathan A. Noquil	07/17/2007										
Ruben Madrid	07/25/2007										
RECEIVING PARTY DATA											
<table border="1"><tr><td>Name:</td><td>Fairchild Semiconductor Corporation</td></tr><tr><td>Street Address:</td><td>82 Running Hill Road, MS 35-4E</td></tr><tr><td>City:</td><td>South Portland</td></tr><tr><td>State/Country:</td><td>MAINE</td></tr><tr><td>Postal Code:</td><td>04106</td></tr></table>		Name:	Fairchild Semiconductor Corporation	Street Address:	82 Running Hill Road, MS 35-4E	City:	South Portland	State/Country:	MAINE	Postal Code:	04106
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PROPERTY NUMBERS Total: 1											
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Application Number:	11829793										
CORRESPONDENCE DATA											
Fax Number: (585)325-5458 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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ATTORNEY DOCKET NUMBER:	3026034										
NAME OF SUBMITTER:	Robert D. Lott										
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OP \$40.00 11829793

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PATENT  
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## ASSIGNMENT

1. The undersigned hereby undertake that the invention/new utility model/new design entitled

**DUAL SIDE COOLING INTEGRATED POWER DEVICE PACKAGE  
AND MODULE AND METHODS OF MANUFACTURE  
(Attorney Docket No. 3026035 (17732.68270.001))**

was truly invented by me/us.

2. The undersigned hereby assign all my/our rights and interests regarding the invention/new utility model/new design, including the right to claim priority, insofar as the Republic of China is concerned to Fairchild Semiconductor Corporation, a corporation organized and existing under the laws of the State of Delaware and located at 82 Running Hill Road, MS 35-4E, South Portland, ME 04106, USA.

Signature 

Name (Print) Jonathan A. Noquil

Date July 17, 2007

Nationality Filipino

Signature \_\_\_\_\_

Name (Print) Ruben Madrid

Date \_\_\_\_\_

Nationality Filipino

Signature \_\_\_\_\_

Name (Print) \_\_\_\_\_

Date \_\_\_\_\_

Nationality \_\_\_\_\_

Signature \_\_\_\_\_

Name (Print) \_\_\_\_\_

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Date \_\_\_\_\_

Nationality \_\_\_\_\_

Signature \_\_\_\_\_

Name (Print) \_\_\_\_\_

Date \_\_\_\_\_

Nationality \_\_\_\_\_

(Neither notarization nor legalization is required for this document)

**FAIRCHILD SEMICONDUCTOR CORPORATION**

**Assignment**

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As a below named inventor or joint inventor of an invention or improvement entitled:

**DUAL SIDE COOLING INTEGRATED POWER DEVICE PACKAGE**  
**AND MODULE AND METHODS OF MANUFACTURE**  
**(Attorney Docket No. 3026034 (17732.68270.001))**

filed on an even date herewith; and

WHEREAS, FAIRCHILD SEMICONDUCTOR CORPORATION, a Corporation, organized and existing under the laws of the State of Delaware, having its principal office and place of business in the City of South Portland, State of Maine, is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I have sold, assigned, transferred, and set over, and by these presents do hereby sell, assign, transfer and set over, unto said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, my entire right, title and interest in, to, and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuation applications thereof, and all Letters Patent of the United States of America which may be granted thereof and all reissues and extensions hereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention, all rights to register said invention in appropriate registries, and all Letters Patent which may be granted for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and I hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, in accordance with the terms of this instrument.


And I hereby covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

Docket:  
3026034 (17732.68270.001)

And I hereby further covenant and agree that I will communicate to said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, any fact known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisions, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN TESTIMONY WHEREOF, I authorize and affirm said assignments with the signature(s) set forth below on the indicated date(s).

Inventors:

  
\_\_\_\_\_  
Jonathan A. Noquil

\_\_\_\_\_  
July 17, 2007  
Date

\_\_\_\_\_  
Ruben Madrid

\_\_\_\_\_  
Date

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Signature \_\_\_\_\_  
Name (Print) Jonathan A. Noquil  
Date \_\_\_\_\_  
Nationality Filipino

Signature   
Name (Print) Ruben Madrid  
Date 25 July 2009  
Nationality Filipino

Signature \_\_\_\_\_  
Name (Print) \_\_\_\_\_  
Date \_\_\_\_\_  
Nationality \_\_\_\_\_

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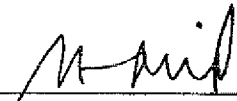
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